

## Electrostatic Discharge가 Magnetoresistive Head의 자기적 특성에 미치는 영향

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### Outline

#### Introduction

#### Experimental

- MR curve tester + "Human Body" ESD simulator
- Sensor temperature during ESD transient

#### Results

- Resistance, amplitude and asymmetry versus ESD voltage, current and energy
- Transfer curve slope reversal
- Magnetic failure before melting

#### Conclusions

### Acknowledgment

#### ◆ Co-Worker:

Al Wallash, Quantum Corp., Milpitas, CA

- A. J. Wallash, and Y. K. Kim, 'Electrostatic Discharge Sensitivity of Giant Magnetoresistive Sensors', *J. Appl. Phys.* 81 (8), 4921 (1997).
- Y. K. Kim, and A. J. Wallash, 'Standardized ESD Testing of AMR and GMR Recording Heads', in *Understanding ESD and EMI Issues in Magnetic Recording*, International Disk Drive Equipment and Materials Association (IDEMA) Symposium, p. 51 (1997).
- A. Wallash and Y. K. Kim, 'Magnetic Changes in GMR Heads Caused by Electrostatic Discharge', *IEEE Trans. Magn.*, To be published (1998).

### Introduction

### Introduction

- GMR sensors are expected to replace AMR sensors
- Handling operations can result in current transients
  - Electrostatic discharge (ESD)
- What is the ESD sensitivity of GMR sensors?
  - Physical melting damage has been studied<sup>1</sup>
  - Are there magnetic changes?

#### GOAL

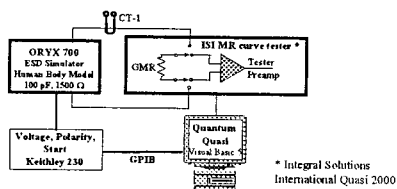
Explore the effects of ESD current transients on the magnetic response of spin valve GMR sensors

1. A. Wallash and Y.K. Kim, *J. Appl. Phys.* 81 (8), 15 April 1997.

### Experimental Setup

#### MR curve tester + ESD simulator

- measurement of the magnetic response of a GMR sensor before and after an ESD current transient



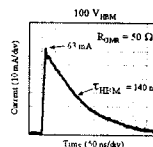
### ESD Simulator

#### "Human Body Model" (HBM) ESD transient

- used widely for ESD testing
- 100 pF, 1500Ω, L ~ 500 nH
- applied across two inputs of GMR read sensor

At each voltage level, two ESD transients were applied

- in the same direction as bias current (+ESD) and opposite (-ESD)



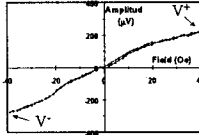
$$I_{peak} = \frac{V_{HBM}}{R_{GMR} + 1500}$$

$$Energy = \frac{I_{peak}^2 R_{GMR} \tau_{HBM}}{2}$$

## MR Curve Testing

### ISI MR curve tester

- flexible and easily integrated with other instruments



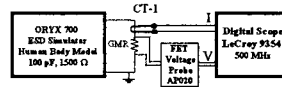
$$\text{Amplitude} = V^+ - V^-$$

$$\text{Asymmetry} = \left[ \frac{V^+ - V^-}{|V^+| + |V^-|} \right] \times 100$$

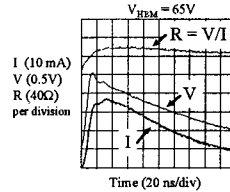
### GMR heads used in this study

- Ta 5/NiFe 7.5/Co 2/Cu 3/Co 2/NiFe 7.5/FeMn 10/Ta 5 nm
- resistance = 30 Ω, stripe height = 1.3 μm, track width = 1.6 μm
- MR test conditions: 5 mA and +/- 40 Oe

## Sensor Temperature during ESD



Measured voltage (V) and current (I) during transient  
 $R(t) = V(t)/I(t)$   
 Use  $R_{peak}$  with TCR to calculate peak temperature



$R(0.1 \text{ mA}) = 33.6 \Omega$   
 $TCR = 0.14\%/^{\circ}\text{C}$   
 For  $V_{HBM} = 65\text{V}$ :  
 $I_{peak} = 41 \text{ mA}$   
 $V_{peak} = 1.8 \text{ V}$   
 $R_{peak} = 52.7 \Omega$   
 $T_{peak} = 425^{\circ}\text{C}$

## Results

### First change at 35 V<sub>HBM</sub>

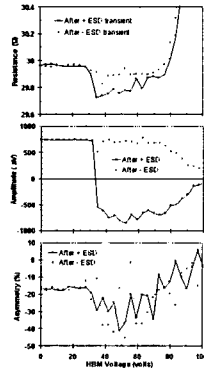
- Small (1%) resistance change
  - nonpermanent and reversible
- Negative amplitude
  - slope reversal
- Asymmetry changes

### Permanent resistance change at 80 V<sub>HBM</sub>

- melting or other physical damage

### Magnetic failure threshold

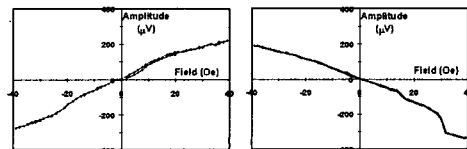
- 35 V<sub>HBM</sub>, 23 mA, 0.9 nJ



## Slope Reversal of MR Curve

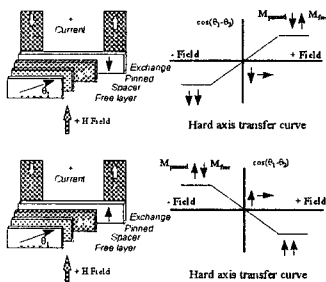
Transfer curve at start and up to 35 V<sub>HBM</sub>

Transfer curve after +35 V<sub>HBM</sub> ESD transient



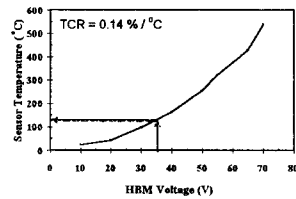
- Slope reversal!
- Asymmetry shift
- Magnetic instability (kink)

## Slope Reversal of Transfer Curve



Slope reversal if pinned layer is reversed.

## Temperature during ESD transient

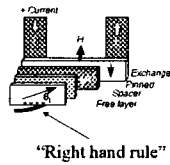


- Slope reversal (magnetic failure) occurred at 35 V<sub>HBM</sub>
- Average calculated sensor temperature = 125 °C
- Consistent with blocking temperature ( $T_b$ ) of FeMn exchange layer (~150 °C)

## ESD $\Rightarrow$ Temperature + Field

### An current transient results in

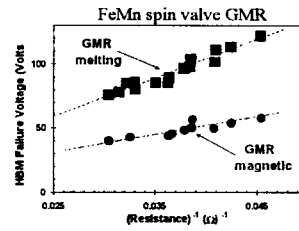
- increased sensor temperature
- an internal magnetic field which can aid (- current) or *oppose* (+ current) the exchange direction



$I_{peak}$	Temperature	Internal H-field	Result
$> 23 \text{ mA}$	$> T_b$	opposite to original direction	Reversed exchange layer
$> -23 \text{ mA}$	$> T_b$	in the original direction	Resets exchange layer back

Therefore the toggling back and forth of the slope

## Melting and Magnetic Failure



Magnetic failure level ~ 40% of the melting failure level

## Conclusions

### ESD stress testing has revealed a new and important magnetic failure mechanism in spin valve GMR heads

- reversal of exchange layer
- magnetic failure levels much lower than melting failure
  - 35 V HBM (magnetic) vs. 80 V HBM (melting)
  - 0.9 nJ (magnetic) vs. 6 nJ (melting)

### Test methodology can be used to compare magnetic failure levels for different spin valve designs

- different exchange materials with higher blocking temperatures